TY Semicondutor®

Product specification

AM2305P

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

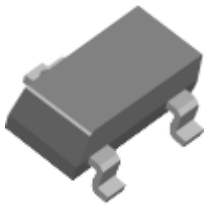
PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (OHM)	I_D (A)
-20	0.043 @ V_{GS} = -4.5V	-4.5
	0.054 @ V_{GS} = -2.5V	-4.0
	0.120 @ V_{GS} = -1.8V	-2.7

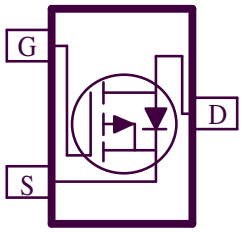
- Low $r_{DS(on)}$ provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SOT-23 saves board space
- Fast switching speed
- High performance trench technology

Pb-free

RoHS COMPLIANT

HALOGEN FREE





ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C UNLESS OTHERWISE NOTED)				
Parameter		Symbol	Ratings	Units
Drain-Source Voltage		V_{DS}	-20	V
Gate-Source Voltage		V_{GS}	±8	
Continuous Drain Current[a]	T_A=25°C	I_D	-4.5	A
	T_A=70°C		-3.6	
Pulsed Drain Current[b]		I_{DM}	-10	
Power Dissipation[a]	T_A=25°C	P_D	1.25	W
	T_A=70°C		0.8	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Maximum	Units
Maximum Junction-to-Ambient[a]	t <= 5 sec	R_{THJA}	100	°C/W
	Steady-State		150	

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. Pulse width limited by maximum junction temperature

SPECIFICATIONS (T_A = 25°C UNLESS OTHERWISE NOTED)						
Parameter	**Symbol**	**Test Conditions**	**Limits**			**Unit**
			Min	**Typ**	**Max**	
Static						
Gate-Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = -250 uA	-0.7			
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±8 V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = -16 V, V_{GS} = 0 V			-1	uA
		V_{DS} = -16 V, V_{GS} = 0 V, T_J = 55°C			-10	
On-State Drain Current[A]	$I_{D(on)}$	V_{DS} = -5 V, V_{GS} = -4.5 V	-10			A
Drain-Source On-Resistance[A]	$r_{DS(on)}$	V_{GS} = -4.5 V, I_D = -3.6 A			43	mΩ
		V_{GS} = -2.5 V, I_D = -3.1 A			54	
		V_{GS} = -1.8 V, I_D = -2.7 A			120	
Forward Tranconductance[A]	g_{fs}	V_{DS} = -5 V, I_D = -1.25 A		12		S
Diode Forward Voltage	V_{SD}	I_S = -0.46 A, V_{GS} = 0 V		-0.60		V
Dynamic[b]						
Total Gate Charge	Q_g	V_{DS} = -5 V, V_{GS} = -4.5 V, I_D = -2.4 A		12.0		nC
Gate-Source Charge	Q_{gs}			2.0		
Gate-Drain Charge	Q_{gd}			2.0		
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = -10 V, I_L = -1 A, V_{GEN} = -4.5 V, R_G = 6 Ω		6.5		ns
Rise Time	t_r			20		
Turn-Off Delay Time	$t_{d(off)}$			31		
Fall-Time	t_f			21		

Notes

a. Pulse test: PW <= 300us duty cycle <= 2%.

b. Guaranteed by design, not subject to production testing.